



# SOT1128-1

plastic thermal enhanced low profile quad flat package; 256 leads; body 28 x 28 x 1.4 mm; heatsink

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HLQFP256
<b>Package type industry code</b>	HLQFP256
<b>Package style descriptive code</b>	HLQFP (thermal enhanced low profile quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-026
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	19-12-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.8	-	28	28.2	mm
E	package width	27.8	-	28	28.2	mm
A	seated height	1.4	-	1.5	1.6	mm
A <sub>2</sub>	package height	1.35	-	1.4	1.45	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	256	-	

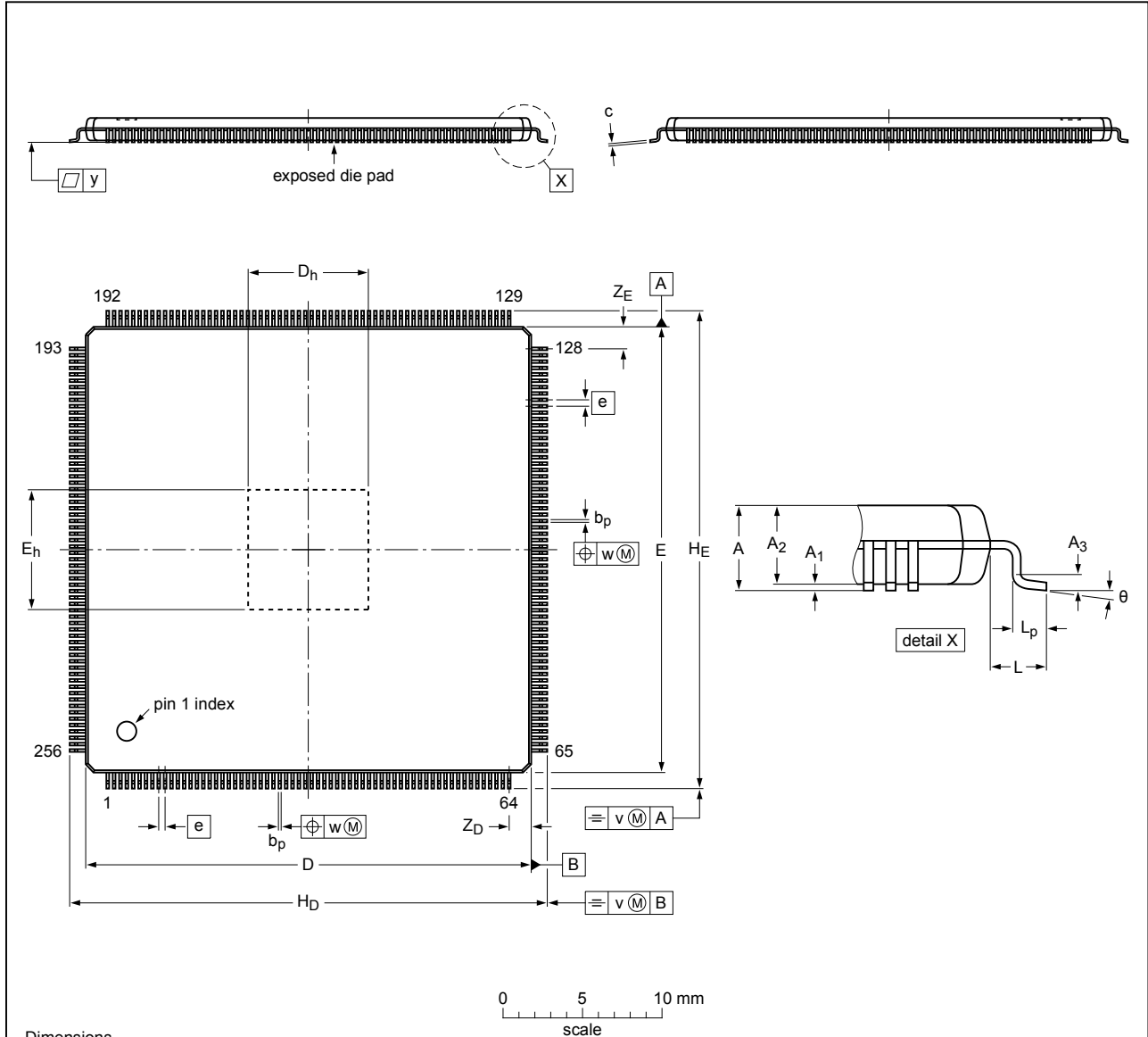


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## 2. Package outline

HLQFP256: plastic thermal enhanced low profile quad flat package; 256 leads; body 28 x 28 x 1.4 mm; exposed die pad

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Dimensions

Unit	A	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
max	1.6	0.15	1.45		0.23	0.20	28.2	7.64	28.2	7.64		30.2	30.2		0.75				1.5	1.5	7.0°
mm nom	1.5	0.10	1.40	0.25	0.18	0.13	28.0	7.54	28.0	7.54	0.4	30.0	30.0	1	0.60	0.2	0.07	0.08	1.4	1.4	3.5°
min	1.4	0.05	1.35		0.13	0.09	27.8	7.44	27.8	7.44		29.8	29.8		0.45				1.3	1.3	0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1128-1		MS-026			08-12-19 10-02-25

Fig. 1. Package outline HLQFP256 (SOT1128-1)

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### 3. Soldering

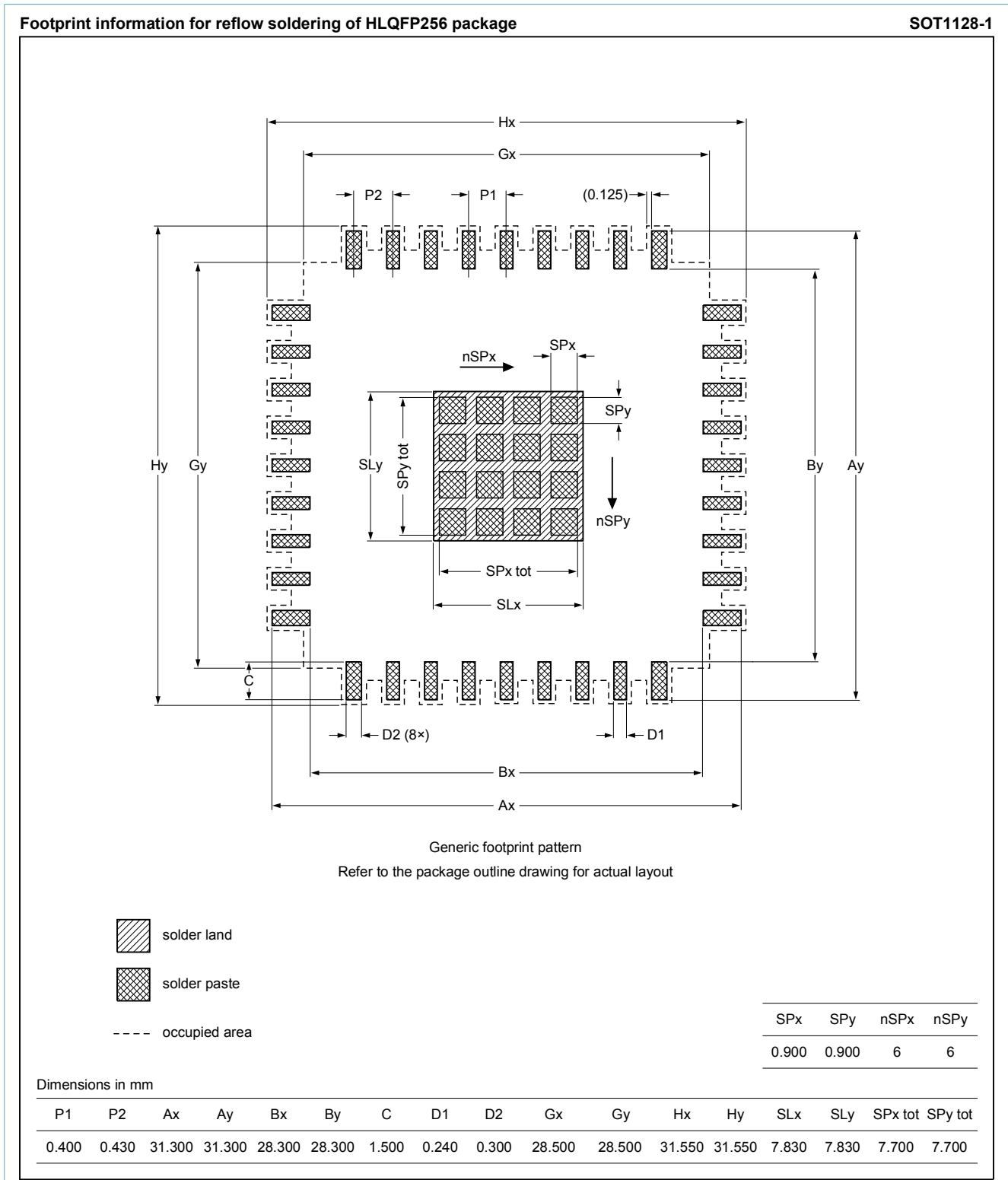


Fig. 2. Reflow soldering footprint for HLQFP256 (SOT1128-1)

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## 4. Legal information

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